

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application:
Rajeev Joshi et al.

Serial No.: 10/731,453

Filed: December 9, 2003

For: WAFER-LEVEL CHIP SCALE PACKAGE AND
METHOD FOR FABRICATING AND USING THE
SAME

Confirmation No. 4432

Group Art Unit: 2891

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Sir:

AMENDMENT AND REQUEST FOR RECONSIDERATION

In response to the Office Action mailed on December 8, 2006, please re-consider this application in light of the following amendments and remarks. Applicants have simultaneously filed a petition for a one-month extension of time to extend the period of response to this Office Action until April 8, 2007.

Amendments to the Claims being on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.